

RF Power Field Effect Transistor

N-Channel Enhancement-Mode Lateral MOSFET

Designed for W-CDMA base station applications with frequencies from 1930 to 1990 MHz. Suitable for TDMA, CDMA and multicarrier amplifier applications. To be used in Class AB for PCN-PCS/cellular radio and WLL applications.

- Typical 2-carrier W-CDMA Performance: $V_{DD} = 28$ Volts, $I_{DQ} = 2 \times 800$ mA, $P_{out} = 38$ Watts Avg., Full Frequency Band, Channel Bandwidth = 3.84 MHz, Peak/Avg. = 8.5 dB @ 0.01% Probability on CCDF.
 Power Gain — 14 dB
 Drain Efficiency — 26%
 IM3 @ 10 MHz Offset — -37.5 dBc @ 3.84 MHz Channel Bandwidth
 ACPR @ 5 MHz Offset — -41 dBc @ 3.84 MHz Channel Bandwidth
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 1960 MHz, 120 Watts CW Output Power
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched, Controlled Q, for Ease of Use
- Qualified Up to a Maximum of 32 V_{DD} Operation
- Integrated ESD Protection
- Lower Thermal Resistance Package
- Low Gold Plating Thickness on Leads, 40 μ ” Nominal.
- In Tape and Reel. R6 Suffix = 150 Units per 56 mm, 13 inch Reel.



1990 MHz, 38 W AVG., 28 V
2 x W-CDMA
LATERAL N-CHANNEL
RF POWER MOSFET

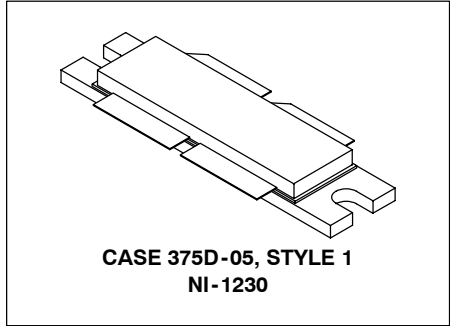


Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +15	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25 $^\circ\text{C}$	P_D	530 3.0	W W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to +150	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$
CW Operation	CW	120	W

Table 2. Thermal Characteristics

Characteristic	Symbol	Value ⁽¹⁾	Unit
Thermal Resistance, Junction to Case Case Temperature 77 $^\circ\text{C}$, 120 W CW Case Temperature 72 $^\circ\text{C}$, 38 W CW	$R_{\theta JC}$	0.33 0.35	$^\circ\text{C}/\text{W}$

1. Refer to AN1955/D, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.

NOTE - CAUTION - MOS devices are susceptible to damage from electrostatic charge. Reasonable precautions in handling and packaging MOS devices should be observed.

Table 3. ESD Protection Characteristics

Test Conditions	Class
Human Body Model	2 (Minimum)
Machine Model	M3 (Minimum)
Charge Device Model	C7 (Minimum)

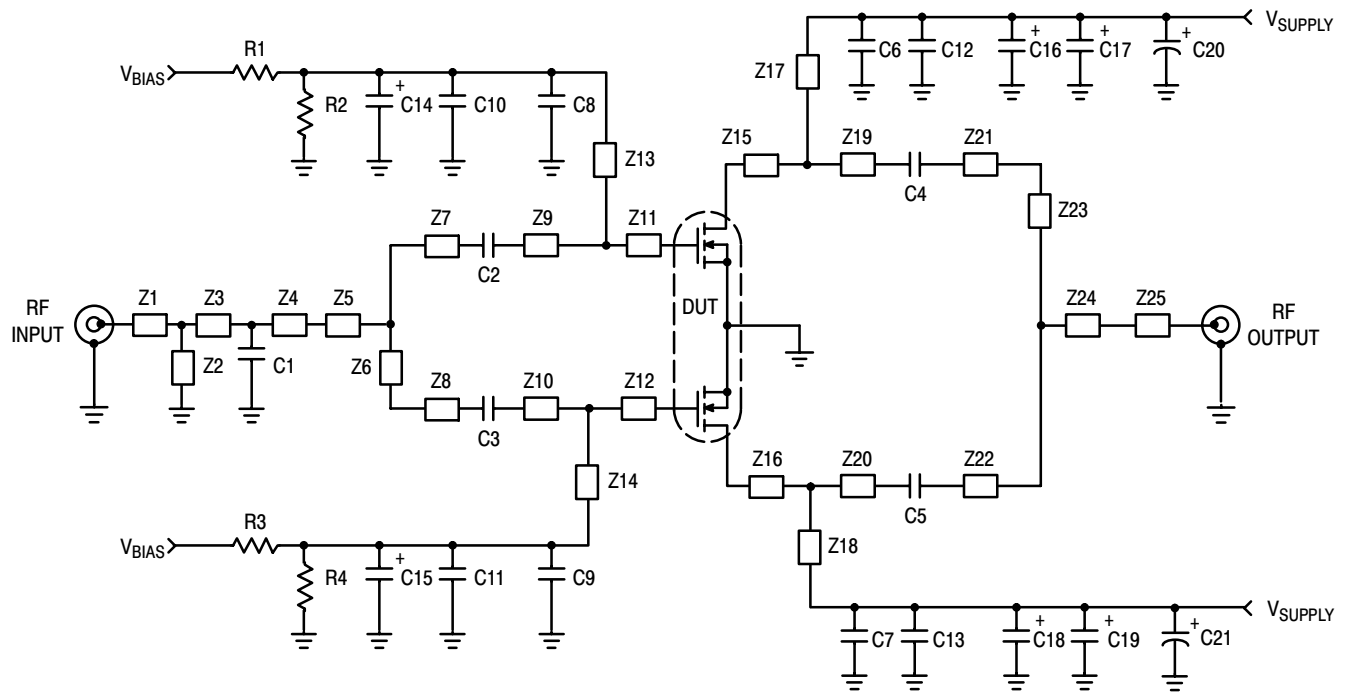
Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Off Characteristics ⁽¹⁾					
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65 \text{ Vdc}$, $V_{GS} = 0 \text{ Vdc}$)	I_{DSS}	—	—	10	μA_{dc}
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28 \text{ Vdc}$, $V_{GS} = 0$)	I_{DSS}	—	—	1	μA_{dc}
Gate-Source Leakage Current ($V_{GS} = 5 \text{ Vdc}$, $V_{DS} = 0 \text{ Vdc}$)	I_{GSS}	—	—	1	μA_{dc}
On Characteristics ⁽¹⁾					
Gate Threshold Voltage ($V_{DS} = 10 \text{ Vdc}$, $I_D = 200 \mu\text{A}_{dc}$)	$V_{GS(th)}$	2.5	2.7	3.5	Vdc
Gate Quiescent Voltage ($V_{DS} = 28 \text{ Vdc}$, $I_D = 850 \text{ mA}_{dc}$)	$V_{GS(Q)}$	—	3.6	—	Vdc
Drain-Source On-Voltage ($V_{GS} = 10 \text{ Vdc}$, $I_D = 2 \text{ A}_{dc}$)	$V_{DS(on)}$	—	0.26	0.3	Vdc
Forward Transconductance ($V_{DS} = 10 \text{ Vdc}$, $I_D = 2 \text{ A}_{dc}$)	g_{fs}	—	5	—	S
Dynamic Characteristics ⁽¹⁾					
Reverse Transfer Capacitance ($V_{DS} = 28 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$)	C_{rss}	—	1.7	—	pF

Functional Tests (In Freescale Test Fixture, 50 ohm system) ⁽²⁾ $V_{DD} = 28 \text{ Vdc}$, $I_{DQ} = 2 \times 800 \text{ mA}$, $P_{out} = 38 \text{ W Avg.}$, $f_1 = 1932.5 \text{ MHz}$, $f_2 = 1942.5 \text{ MHz}$ and $f_1 = 1977.5 \text{ MHz}$, $f_2 = 1987.5 \text{ MHz}$, 2-carrier W-CDMA, 3.84 MHz Channel Bandwidth Carriers. ACPR measured in 3.84 MHz Channel Bandwidth @ $\pm 5 \text{ MHz}$ Offset. IM3 measured in 3.84 MHz Bandwidth @ $\pm 10 \text{ MHz}$ Offset. Peak/Avg. = 8.5 dB @ 0.01% Probability on CCDF.

Power Gain	G_{ps}	12.5	14	—	dB
Drain Efficiency	η_D	23	26	—	%
Intermodulation Distortion	IM3	—	-37.5	-35	dBc
Adjacent Channel Power Ratio	ACPR	—	-41	-38	dBc
Input Return Loss	IRL	—	-16	-9	dB

1. Each side of device measured separately. Part is internally matched both on input and output.
2. Measurements made with device in push-pull configuration.

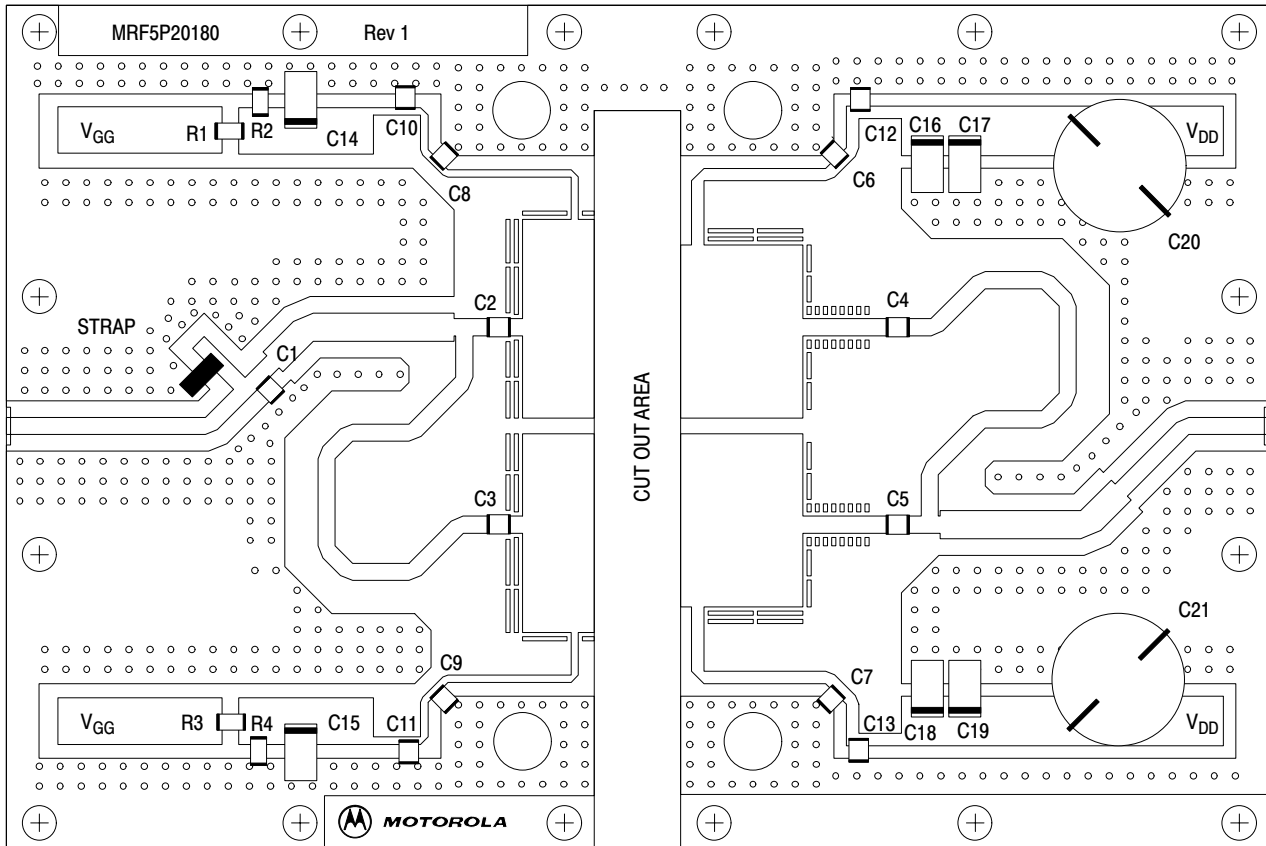


Z1	0.081" x 1.126" Microstrip	Z11, Z12	0.341" x 0.945" Microstrip
Z2	0.079" x 0.138" Microstrip	Z13, Z14	0.035" x 0.913" Microstrip
Z3	0.081" x 0.091" Microstrip	Z15, Z16	0.581" x 0.823" Microstrip
Z4	0.081" x 0.117" Microstrip	Z17, Z18	0.059" x 1.057" Microstrip
Z5, Z24	0.134" x 0.874" Microstrip	Z19, Z20	0.081" x 0.046" Microstrip
Z6, Z23	0.081" x 2.269" Microstrip	Z21, Z22	0.081" x 0.126" Microstrip
Z7, Z8	0.081" x 0.118" Microstrip	Z25	0.081" x 0.793" Microstrip
Z9, Z10	0.081" x 0.079" Microstrip	PCB	Taconic TLX8-0300, 0.030", $\epsilon_r = 2.55$

Figure 1. MRF5P20180HR6 Test Circuit Schematic

Table 5. MRF5P20180HR6 Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
C1	1.8 pF 100B Chip Capacitor	100B1R8BW	ATC
C2, C3, C4, C5, C6, C7	10 pF 100B Chip Capacitors	100B100GW	ATC
C8, C9	6.8 pF 100B Chip Capacitors	100B6R8CW	ATC
C10, C11, C12, C13	10 nF 200B Chip Capacitors	200B103MW	ATC
C14, C15, C16, C17, C18, C19	22 μ F, 35 V Tantalum Capacitors	TAJE226M035	AVX
C20, C21	220 μ F, 63 V Electrolytic Capacitors	13668221	Philips
R1, R2, R3, R4	10 k Ω Chip Resistors (1206)		



Freescle has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescle Semiconductor signature/logo. PCBs may have either Motorola or Freescle markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. MRF5P20180HR6 Test Circuit Component Layout

TYPICAL CHARACTERISTICS

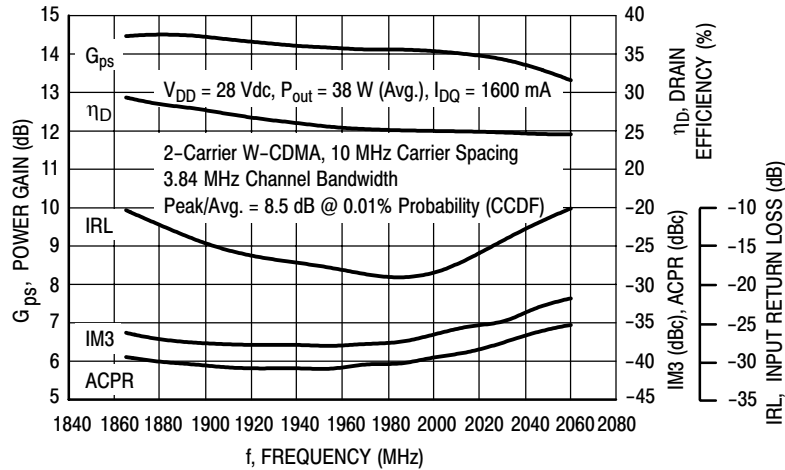


Figure 3. 2-Carrier W-CDMA Broadband Performance

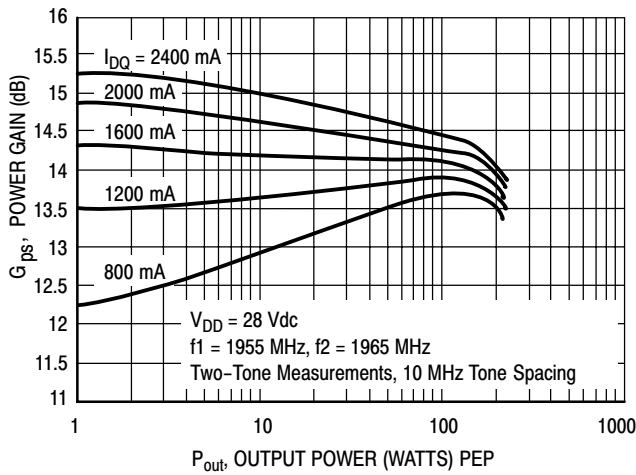


Figure 4. Two-Tone Power Gain versus Output Power

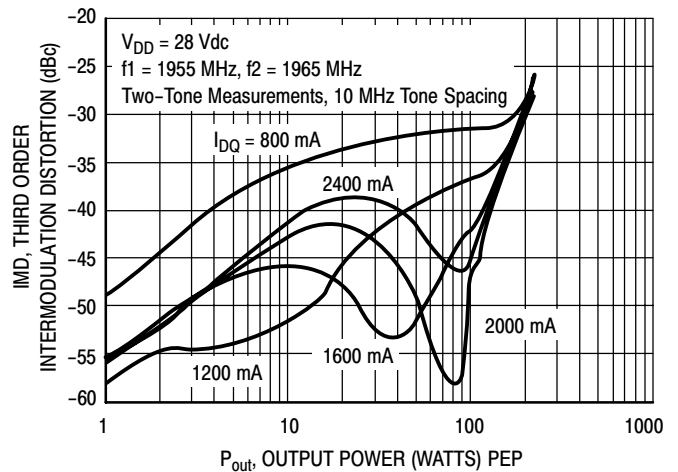


Figure 5. Third Order Intermodulation Distortion versus Output Power

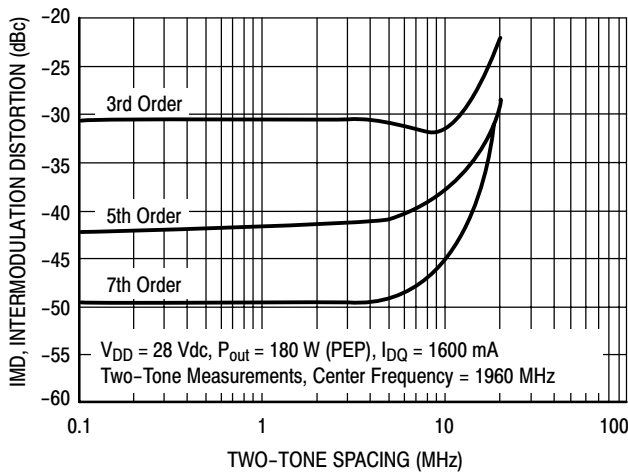


Figure 6. Intermodulation Distortion Products versus Tone Spacing

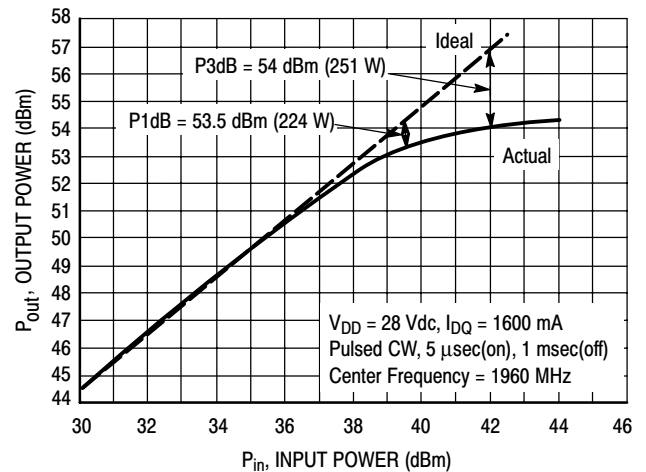


Figure 7. Pulse CW Output Power versus Input Power

TYPICAL CHARACTERISTICS

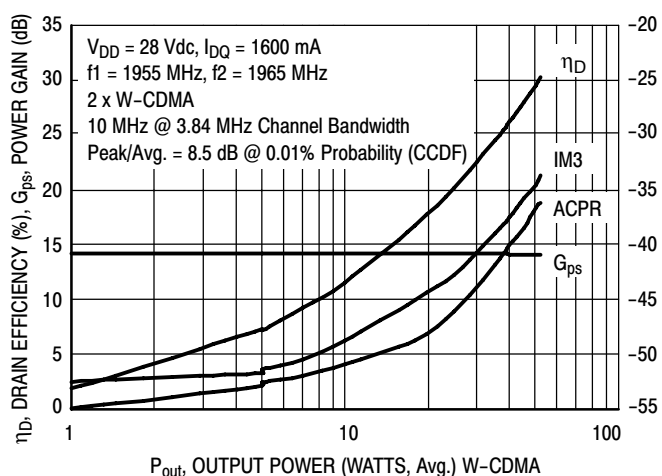
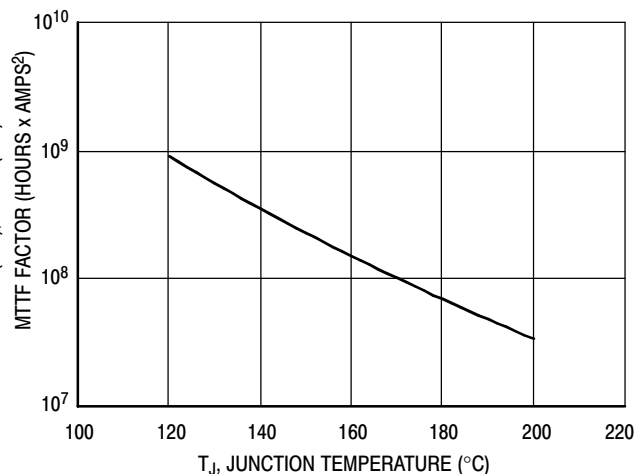


Figure 8. 2-Carrier W-CDMA ACPR, IM3, Power Gain and Drain Efficiency versus Output Power



This above graph displays calculated MTTF in hours x ampere² drain current. Life tests at elevated temperatures have correlated to better than $\pm 10\%$ of the theoretical prediction for metal failure. Divide MTTF factor by I_D^2 for MTTF in a particular application.

Figure 9. MTTF Factor versus Junction Temperature

W-CDMA TEST SIGNAL

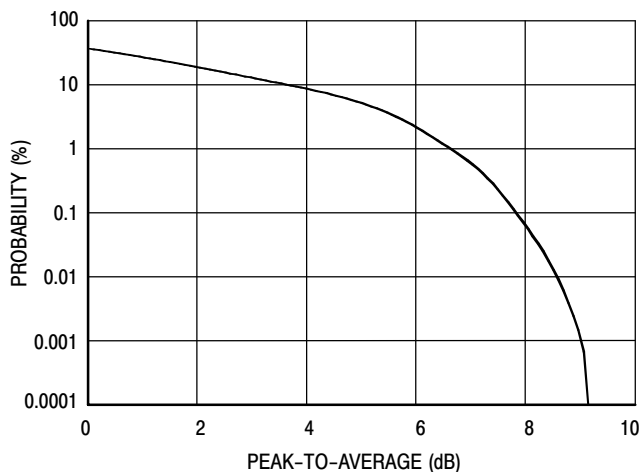


Figure 10. CCDF W-CDMA 3GPP, Test Model 1, 64 DPCH, 67% Clipping, Single Carrier Test Signal

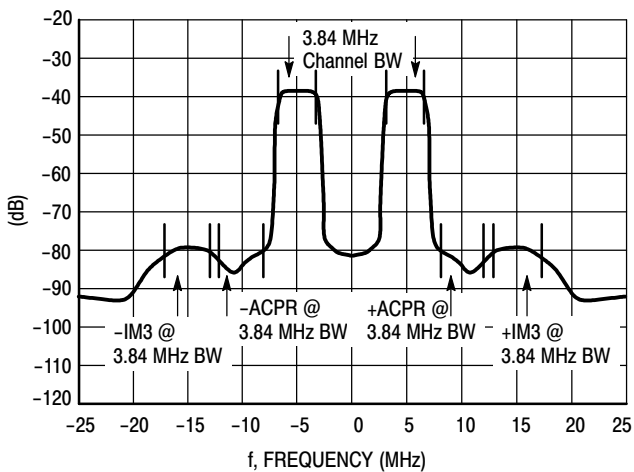
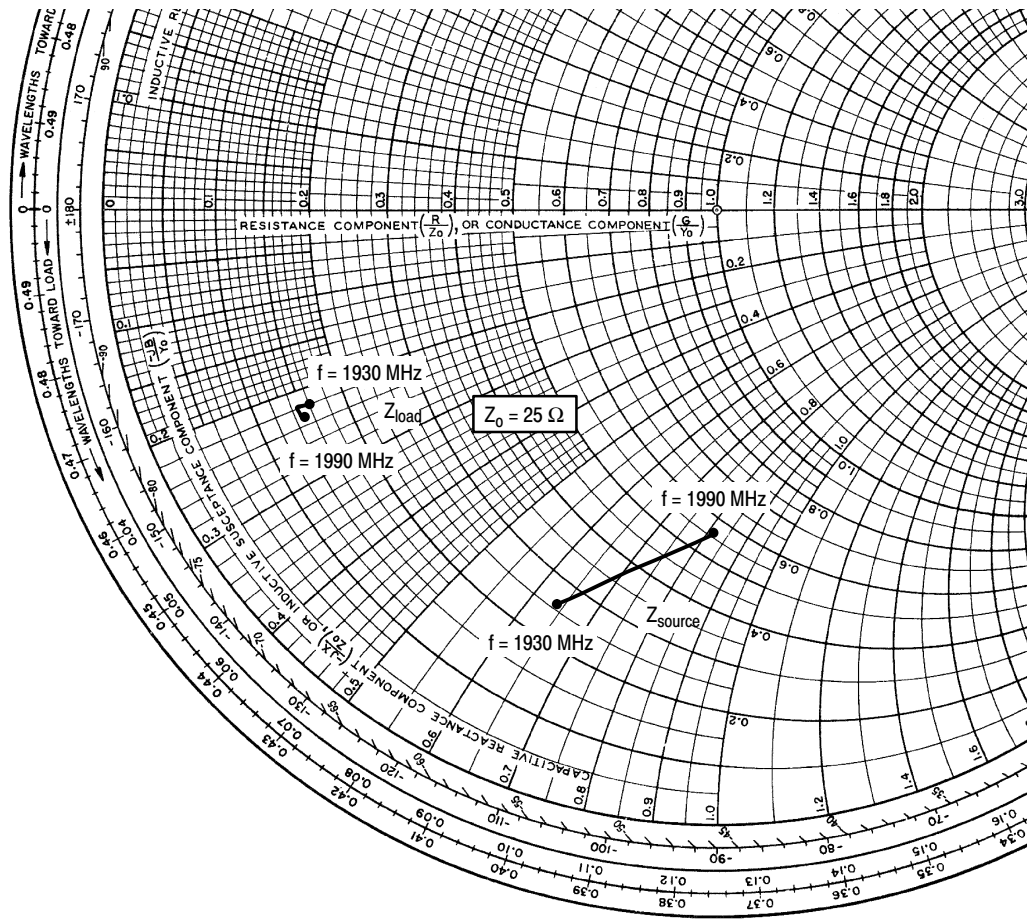


Figure 11. 2-Carrier W-CDMA Spectrum



$V_{DD} = 28\text{ V}$, $I_{DQ} = 2 \times 800\text{ mA}$, $P_{out} = 38\text{ W Avg.}$

f MHz	Z_{source} Ω	Z_{load} Ω
1930	$6.54 - j16.04$	$4.06 - j5.56$
1960	$9.70 - j17.92$	$3.70 - j5.48$
1990	$13.88 - j20.46$	$3.64 - j5.76$

Z_{source} = Test circuit impedance as measured from gate to gate, balanced configuration.

Z_{load} = Test circuit impedance as measured from drain to drain, balanced configuration.

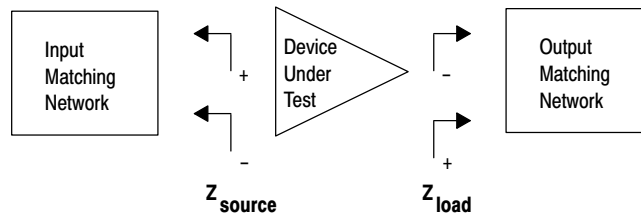


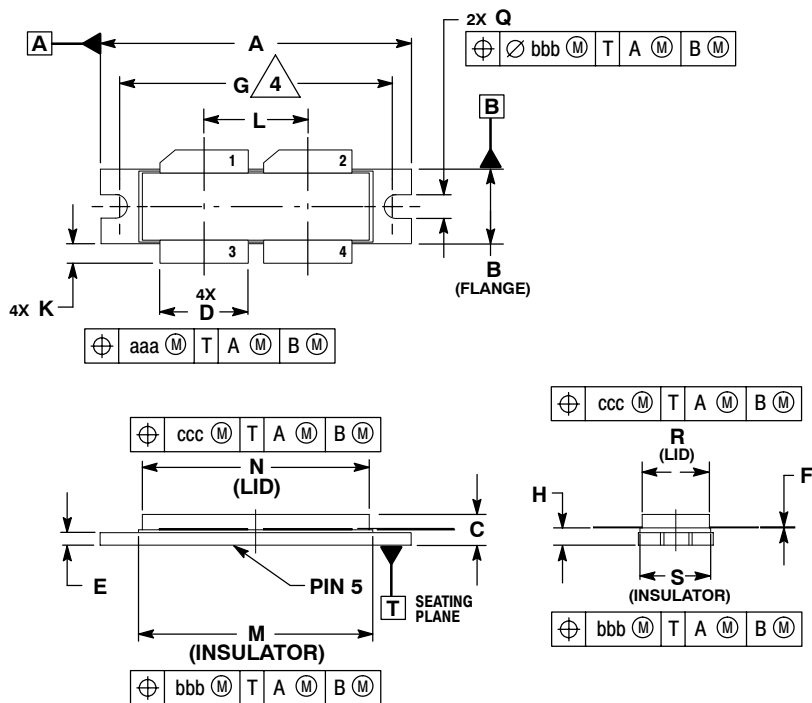
Figure 12. Series Equivalent Source and Load Impedance

NOTES

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PACKAGE DIMENSIONS



- NOTES:
1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
 4. RECOMMENDED BOLT CENTER DIMENSION OF 1.52 (38.61) BASED ON M3 SCREW.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.615	1.625	41.02	41.28
B	0.395	0.405	10.03	10.29
C	0.150	0.200	3.81	5.08
D	0.455	0.465	11.56	11.81
E	0.062	0.066	1.57	1.68
F	0.004	0.007	0.10	0.18
G	1.400 BSC		35.56 BSC	
H	0.082	0.090	2.08	2.29
K	0.117	0.137	2.97	3.48
L	0.540 BSC		13.72 BSC	
M	1.219	1.241	30.96	31.52
N	1.218	1.242	30.94	31.55
Q	0.120	0.130	3.05	3.30
R	0.355	0.365	9.01	9.27
S	0.365	0.375	9.27	9.53
aaa	0.013 REF		0.33 REF	
bbb	0.010 REF		0.25 REF	
ccc	0.020 REF		0.51 REF	

- STYLE 1:
1. DRAIN
 2. DRAIN
 3. GATE
 4. GATE
 5. SOURCE

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